# ACCELERATE®HD HIGH-DENSITY SLIM BODY ARRAYS (0.635 mm) .025" PITCH

## **FEATURES & BENEFITS**

- Up to 400 positions in 4-row design
- 5 mm, 7 mm, 9 mm, 10 mm, 11 mm, 12 mm 14 mm & 16 mm stack heights
- Slim 5 mm width body design
- Edge Rate<sup>®</sup> contact system optimized for signal integrity performance
- Open-pin-field for grounding and routing flexibility
- PCIe<sup>®</sup> 5.0 capable
- Compatible with mPower<sup>®</sup> (UMPT/UMPS) for a power signal solution

## PAM4 56 <sub>G b p s</sub>



Solder ball technology for simplified processing

#### HIGHER DENSITY THAN PREVIOUS GENERATION STRIPS



### **KEY SPECIFICATIONS**

РІТСН	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
(0.635 mm) .025"	40 - 400	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 ℃ to +125 ℃	1.34 A per pin (4 pins powered)	Testing now	Yes

#### samtec.com/AcceleRateHD

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.



#### (0.635 mm) .025" PITCH • SLIM BODY OPEN-PIN-FIELD ARRAYS



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	MATED HEIGHTS *								
I	ADF6	ADM6 LEAD STYLE							
	LEAD STYLE	-01.5	-03.5	-06.5	-08.5				
-	-03.5	(5 mm) .197"	(7 mm) .276"	(10 mm) .394"	(12 mm).472"				
	-07.5	(9 mm) .354"	(11 mm) .433"	(14 mm) .551"	(16 mm).630"				

\* Processing conditions will affect mated height.

### ADF6

Board Mates: ADM6

Standoffs: JSO







Notes: Some sizes, styles and

options are non-standard, non-returnable

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